Title of Document: HANDLING MANUAL	Issue No. CHM-1-2316	Rev. 1
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Title subject: AGH Connector	Revision date: April 10, 2020	

This manual describes important and required points of handling about AGH connector.
Be sure to read this manual thoroughly before using AGH connector.

CONTENTS

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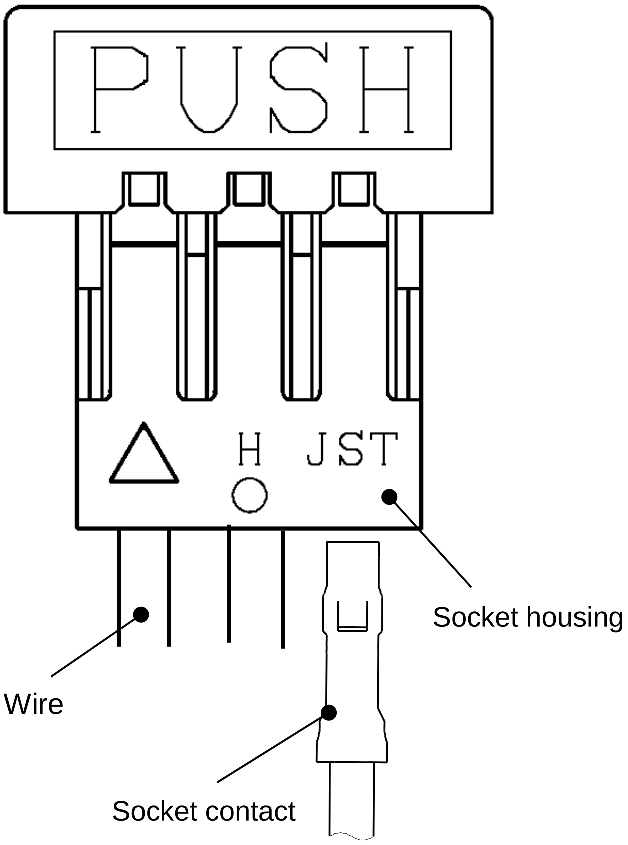
1. Model Number and Part Name

1-1 Model number

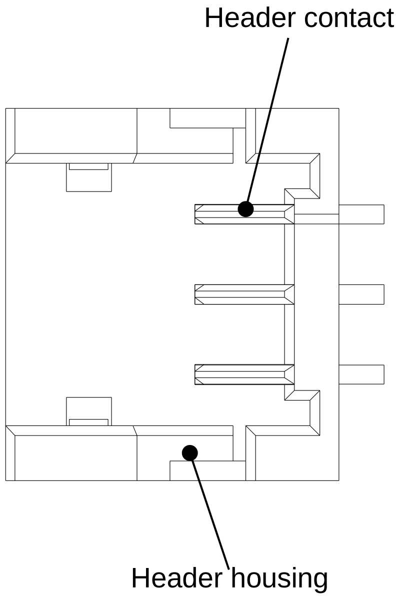
Part name		Model No.
Header	Taping product	BM03B∗-AGHS-( )-TF (LF)(SN)
	Loose piece product	BM03B∗-AGHS-( ) (LF)(SN)
Socket	Contact	SAGH-002GU-P0.3
	Housing	AGHR-03V-1-H

Note$_1$: Figures in ∗ denote the height.
Note$_2$: Letters in ( ) denote the plating specification.
GG: Nickel-undercoated partial gold plating (0.4 µm or more)
GH: Nickel-undercoated partial gold plating
(0.4µm or more at the contact area, flash at the solder tail part)

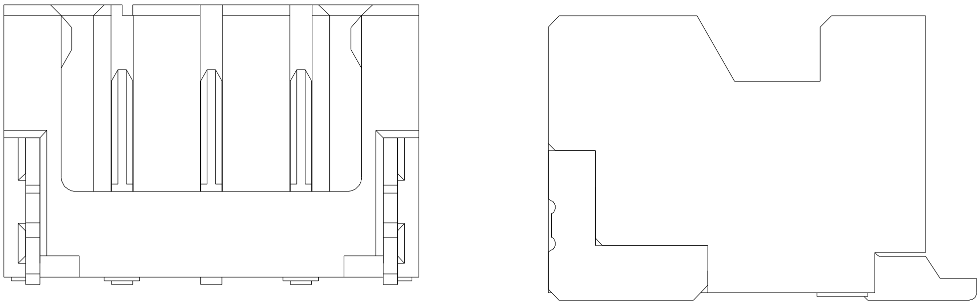
1-2 Part name



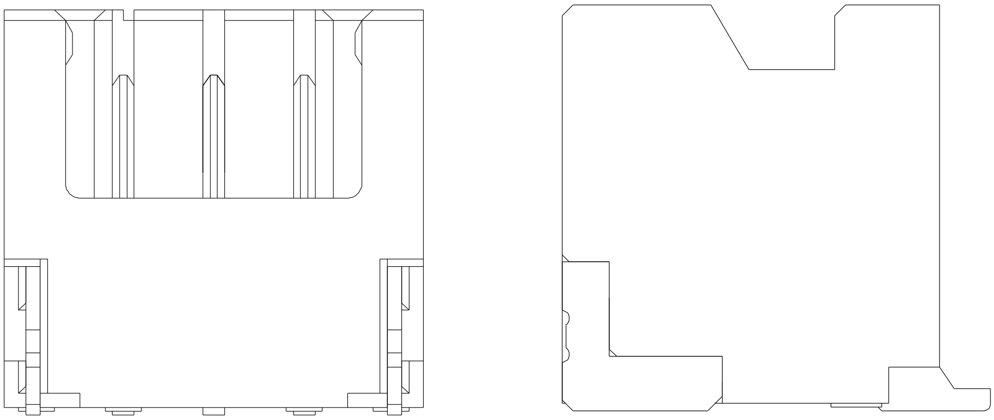
Socket



3.9mm height



5.6mm height



<u>Header</u>

2. Storage

2-1 Connector storage

Recommended storage condition: Temperature: 5 – 35 ˚C, Relative humidity 60 % or less
(Under packaging like the state of JST shipment)

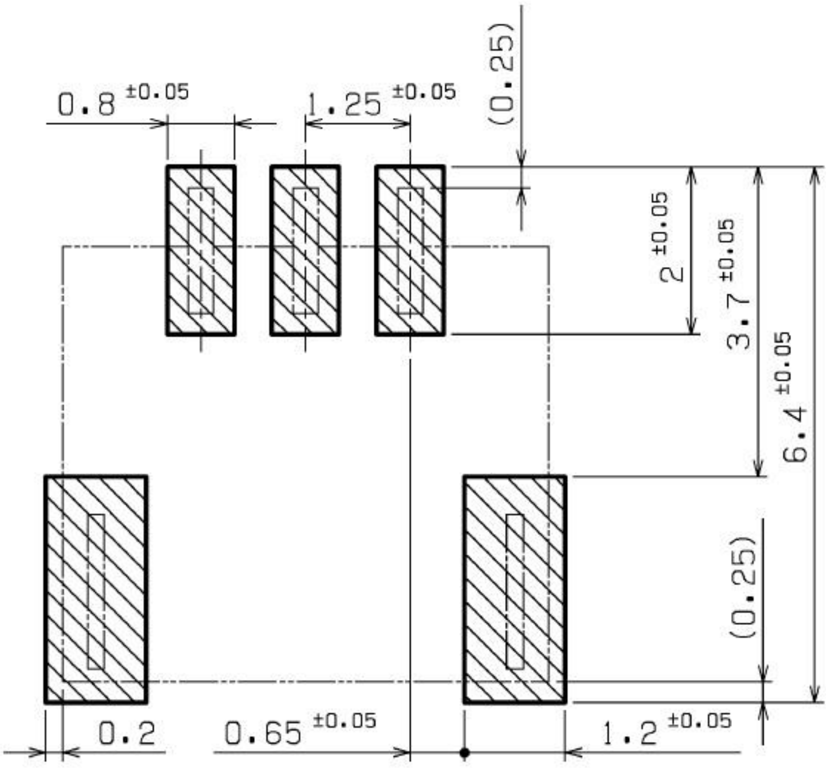
Keep off direct sunlight, places exposing to such corrosive gas as industrial gas (generate from a stove and whatnot) and ammonia gas (generate from a toilet and whatnot), dusty place and condensation.

Note that the resin molding part may break due to transportation and handling, such as processing and mating, under dry or low temperature condition.
After unpacking, return products in the original package to store.

2-2 Storage of the processed products

Not leaving the processed products to stand in a place exposed to high humidity and direct sunshine, and not placing them directly on the ground, keep them in a clean storage room.

3. PC Board Pattern Layout



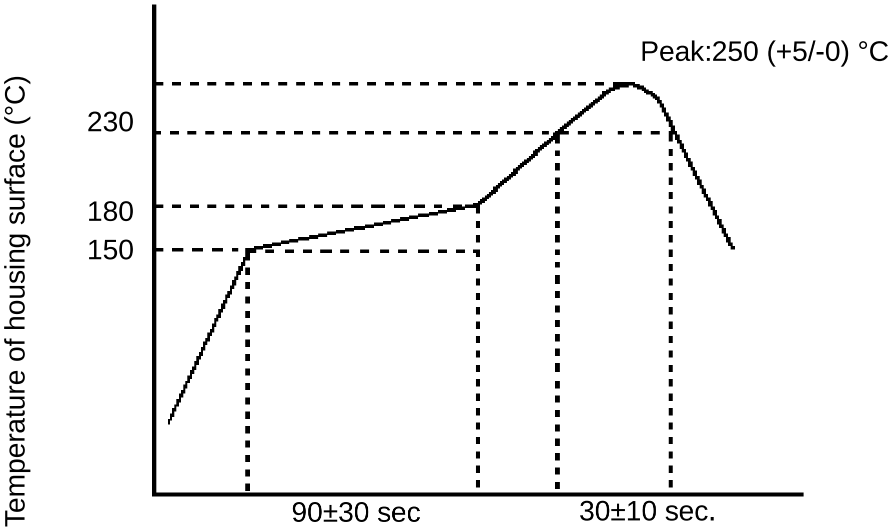
4. Precautions for Mounting Connector on PC Board

Pay careful attention to the following points for mounting the connector on PC board.

4-1 Reflow soldering method

We recommend reflow soldering at lower temperature than the temperature profile shown below.
As the recommended reflow temperature condition varies depending on the materials, such as solder paste, solder the connector according to the condition of the material.

We recommend using the 0.1 to 0.15 mm-thick metal mask which area of the blanking part is same as PC board pad area. In case that the metal mask thickness is more than 0.15 mm, adjust the amount (area) of soldering coat by making the opening area smaller than the PC board pad area.



Temperature profile for reflow soldering

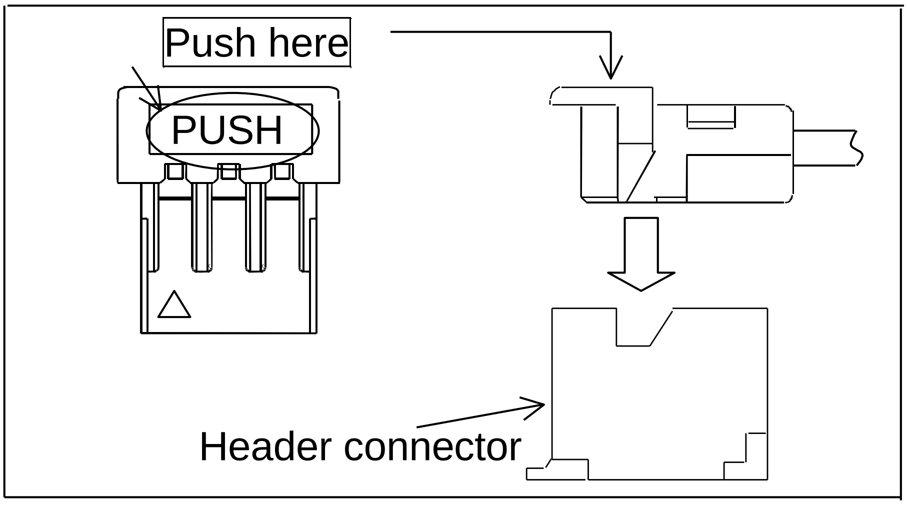
4-2 Soldering iron method

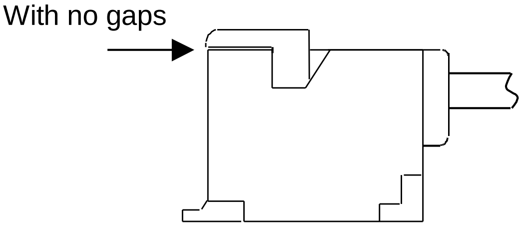
Solder the connector or repair soldering by using a soldering iron of 350°C quickly within 3 seconds.
When soldering, do not push the iron tip on the connector contact lead part nor apply an abnormal force such as lateral load. If done, dismount and replace the connector with the new one.
Do not reuse the dismounted connector.

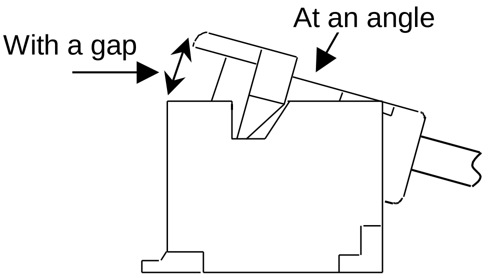
5. Handling Precautions

5-1 Mating operation

Mate the socket connector with the header one on the same axis. Be sure to push the “PUSH” part of the socket connector and check secure mating of the connector.







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Mating condition

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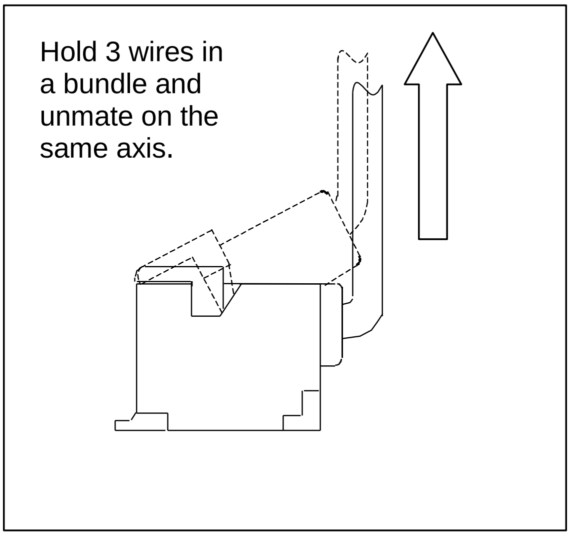
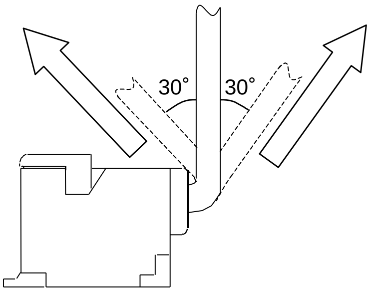
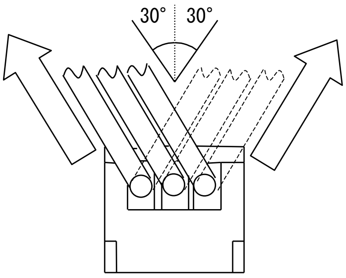
Incomplete mating condition
(Electrical discontinuity)

5-2 Unmating operation

Hold 3 wires in a bundle and unmate the socket connector from the header on the same axis.
At this time, do the operation within 30 degrees to the mating axis.

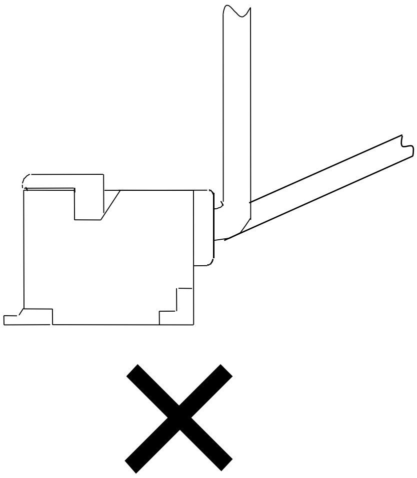


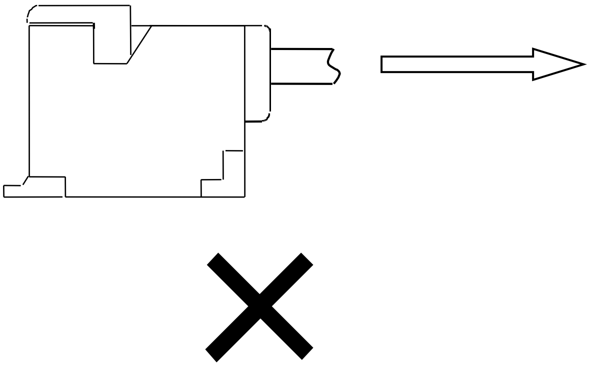




Points to be noted

In unmating the connector, do not hold only several wires or do not pull wires perpendicularly to the mating direction, because the contact is deformed or the housing cracks or chips, leading to connector troubles.





5-3 Handling wires

Give consideration for not applying to the connectors tension stemmed from wire bending.
(Keep a distance from the connector and do wire forming not to apply tension.)